

Exploratory Materials* for Origin Open Material License (OML)



Name	Material Supplier	Category	Description	Sample Applications	More Info
PerFORM HW	Covestro	High Temperature	High stiffness, high temp, ceramic-filled resin (Tg 160°C Flex modulus 8,700 MPa)	High-temp injection molds	Covestro
RG1100	BASF Forward AM	High Temperature	High temperature, rigid and fast-printing resin (HDT 116°C Flex modulus 2,880 MPa)	Molds or durable engineering parts	Forward AM
CorAlpha	polySpectra	High Temperature	High temperature resin with good elongation (HDT 115°C 20% E@B)	Bearing and gear components	Polyspectra
RG 3101 L	Evonik	Tough	Well-balanced resin with good stiffness, impact strength, and HDT (Izod 45 J/m Tg 105°C)	Buckles and rivets	Evonik 3D Printing
Strong-X	Liqcreate	Tough	High stiffness resin (Tg 128°C Flex modulus 3,500 Mpa)	Heavy duty components	Liqcreate
Formula One	Mechnano	Specialty	Rigid resin with ESD properties (Surface resistivity of 10 ^{^8} Ω)	Electrical housings, PCB carriers	Mechnano
Komitsudo Ceramic	Tethon3D	Specialty	Rigid high temp ceramic-filled resin (Max temp 1,700°C)	Aerospace Thermal Shields	Tethon 3D
CAST011	Arkema	Specialty	High detail, burnout castable resin (Viscosity 115 cP)	Cast structural brackets	Arkema DLP

* OML users can develop or print any DLP materials available to them. For more information on these materials, please contact material suppliers directly.

